



## Final Product Change Notification

202102035F01 : GTL2014PW Conversion to Roughened Lead Frame and Wire Size Consolidation

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Jul 21, 2021 **Effective date:** Oct 12, 2021

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### Management summary

GTL2014PW devices will convert to a roughened leadframe for improved package reliability. Additionally, the wire size will change to 18u diameter for material standardization which will de-risk potential delays due to material imbalances.

### Change Category

- Wafer Fab Process
- Assembly Process
- Product Marking
- Test Process
- Design
- Wafer Fab Materials
- Assembly Materials
- Mechanical Specification
- Test Equipment
- Errata
- Wafer Fab Location
- Assembly Location
- Packing/Shipping/Labeling
- Test Location
- Electrical spec. Test coverage
- Firmware
- Other

## PCN Overview

### Description

ATBK will convert GTL2014PW to a roughened leadframe for quality improvement and will consolidate wire sizes (20u, 25u) to 18u. With the use of roughened lead frames, the product data sheets will be updated and available on the NXP website showing a new orderable part number reflecting the use of Static Shielding Bags (SSB).

### Reason

The roughened leadframe offers superior delamination performance after customer SMT. Conversion to 18u de-risks potential line-downs due to material imbalances and improves manufacturing efficiencies by consolidating wire size.

### Identification of Affected Products

Product identification does not change

### Product Availability

### Sample Information

Samples are available upon request

## Production

Planned first shipment Sep 27, 2021

## Anticipated Impact on Form, Fit, Function, Reliability or Quality

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No Impact on form, fit, function, reliability or quality

### Data Sheet Revision

A new datasheet will be issued

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Additional information

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Self qualification: [view online](#)

## Timing and Logistics

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In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Aug 20, 2021.

## Contact and Support

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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